

**LTM8001 121 LD-BGA-PBF 15mm X 15mm X 3.42mm -SOLDER DA(TABLE OF MATERIAL DECLARATION)**

*The LTM8001 is RoHS compliant per EU RoHS Directive 2003/95/EC.*

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2486	Barium Compounds	7727-43-7	0.00631	2.54
				Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1 1156-51-0/9003-36-5/21645-51-2 non-disclosure	0.04723	19.00
				Copper Metal	7440-50-8	0.14125	56.82
				Copper Compounds	147-14-8	0.00005	0.02
				Ecotoxic substances	7440-38-2 7440-28-0	0.00002	0.01
				Gold metal or alloy	7440-57-5	0.00040	0.16
				Nickel	7440-02-0	0.00189	0.76
				Zinc	7440-66-6	0.00027	0.11
				Continuous Filament Fiber Glass	65997-17-3	0.03712	14.93
				Acrylic Resin	non-disclosure	0.01203	4.84
				Epoxy Resin	non-disclosure	0.00005	0.02
				Chromium (III) oxide	1308-38-9	0.00001	0.00
				Silica amorphous	7631-86-9	0.00014	0.06
				Talcinot containing fibers like asbestos	14807-96-6	0.00072	0.29
				Arcomatic carbonyl compounds	non-disclosure	0.00070	0.28
				Cyanoguanidine	461-58-5	0.00002	0.01
				Calcium Caobonate	471-34-1	0.00001	0.00
				Amine compounds	non-disclosure	0.00009	0.04
				Leveling agent and others	non-disclosure	0.00027	0.11
				2	Solder Paste	Alloy	0.0280
Sb	7440-36-0	0.00140	5.00				
3	Passive/Active Components		0.5253	Iron Powder (Fe)	7439-89-6	0.35794	68.15
				Copper (Cu)	7440-50-8	0.10978	20.90
				Nickel (Ni)	7440-02-0	0.00684	1.30
				Tin (Sn)	7440-31-5	0.00466	0.89
				Ceramic (Ba) Compounds	12047-27-7	0.04607	8.77
4	Active Ics	Silicon	0.0125	Silicon	7440-21-3	0.01247	100.00
5	Wire	Gold	0.0006	Au	7440-57-5	0.00064	99.99
6	Solder Ball	SAC305	0.2030	Sn	7440-31-5	0.19594	96.50
				Ag	7440-22-4	0.00609	3.00
				Cu	7440-50-8	0.00102	0.50
7	Encapsulation	Epoxy Resin	0.8077	Fused Silica	60676-86-0	0.62358	77.20
				Epoxy Resin	non-disclosure	0.07189	8.90
				Phenol Resin	non-disclosure	0.07189	8.90
				Crytalline Silica	14808-60-7	0.02423	3.00
				Carbon Black	1333-86-4	0.00404	0.50
				Metal Hydroxide	non-disclosure	0.01212	1.50
Total Package Weight			1.8258				

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts